



Final Product Change Notification

202306039F01 : MC9S08LC60/36LK LQFP80 Assembly Site Expansion from ASECL to TFME

Note: This notice is NXP Company Proprietary.

Issue Date: Aug 11, 2023 **Effective date:** Nov 09, 2023

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For detailed information we invite you to view this notification online

Management summary

Assembly site expansion for MC9S08LC60/36LK LQFP80 parts associated with this notification from the current ASE, Chung Li, Taiwan (ASE-CL) assembly facility to TongFu Microelectronics Co.,Ltd, Nantong. China (TFME) assembly facility.

Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input checked="" type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input checked="" type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware <input type="checkbox"/> Other				

PCN Overview

Description

NXP Semiconductors announces the Assembly site expansion for MC9S08LC60/36LK LQFP80 parts associated with this notification from the current ASE, Chung Li, Taiwan (ASE-CL) assembly facility to TongFu Microelectronics Co.,Ltd, Nantong. China (TFME) assembly facility.

Please see attached files for additional details.

Reason

Qualification of TFME is required for manufacturing flexibility and customer supply assurance.

Identification of Affected Products

Top Side Marking

The assembly site, among other information, is reflected in the package trace code.

The format for the NXP standard trace code: AWLYYWWZ is the following:

A=Assembly Site, WL=Wafer Lot, YY=Year, WW=Work Week, Z= Assembly Split Lot.

The current assembly site marking for ASE-CL is A = X

The marking for proposed assembly site TFME is A = XN

Product Availability

Sample Information

Samples are available upon request

Samples with part number PC9S08LC60LK will be provided upon request.

Production

Planned first shipment Nov 10, 2023

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Disposition of Old Products

Assembly site expansion. No depletion of Inventory required.

Additional information

Self qualification: view online

Additional documents: view online

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Sep 10, 2023.

Remarks

TFME LQFP80 12x12 has two Eject Pins Dot while ASE-CL doesn't have Eject Pins Dot in the top side.

Detailed information is shown in attachment "LC60 LQFP80 12x12 Visual Comparison of ASE-CL V.S TFME.pdf"

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name	Wang Runna
Position	Product Engineer
e-mail address	runna.wang@nxp.com

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NXP Quality Management Team.

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NXP Semiconductors

High Tech Campus, 5656 AG Eindhoven, The Netherlands

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Orderable Part Number#	12NC	Product Type	Product Description	Package Outline	Package Description	Product Status	Customer Specific Indicator	Product Line
MC9S08LC60LK	935319018557	MC9S08LC60LK	8 BIT, 60K FLASH-LOW VOL	(L)QFP80	SOT315-2	RFS	No	BLM1
MC9S08LC36LK	935321022557	MC9S08LC36LK	8 BIT, 36K FLASH-LOW VOL	(L)QFP80	SOT315-2	RFS	No	BLM1